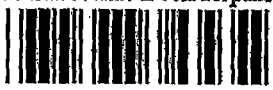
ABSTRACT OF THE INVENTION

A semi-conductor package in which an integrated circuit chip is connected to a substrate using wire-bonding is prepared by curing the die attach adhesive and encapsulating the wire bonds in one heating step. The encapsulant composition has a curing chemistry and a curing profile compatible with those of the adhesive.

This Sheet Has Been Replaced



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